

March 2013

# FCP380N60 / FCPF380N60 N-Channel SuperFET $^{\mbox{\scriptsize R}}$ II MOSFET 600 V, 10.2 A, 380 m $\Omega$

#### **Features**

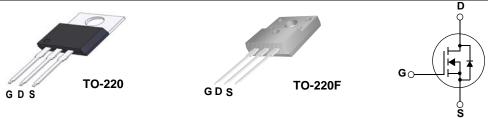
- 650 V @T<sub>J</sub> = 150°C
- Max.  $R_{DS(on)} = 380 \text{ m}\Omega$
- Ultra low gate charge (typ.  $Q_g = 30 \text{ nC}$ )
- Low effective output capacitance (typ. Coss.eff = 95 pF)
- 100% avalanche tested

# **Applications**

- LCD / LED / PDP TV Lighting
- · Solar Inverter
- AC-DC Power Supply

## **Description**

SuperFET<sup>®</sup>II MOSFET is Fairchild Semiconductor <sup>®</sup>,'s first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. Consequently, SuperFETII MOSFET is suitable for various AC/DC power conversion for system miniaturization and higher efficiency.



#### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol		Parameter		FCP380N60	FCPF380N60	Unit	
V <sub>DSS</sub>	Drain to Source Voltage				600		
\ <i>I</i>	Cata ta Cauraa Valtaga	-DC		±	20	V	
$V_{GSS}$	Gate to Source Voltage	-AC	(f >1 HZ)	±	30	V	
	Drain Current	-Continuous (T <sub>C</sub> = 25°C)		10.2	10.2*	^	
ID	Drain Current	-Continuous (T <sub>C</sub> = 100°C)		6.4	6.4*	Α	
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	30.6	30.6*	Α	
E <sub>AS</sub>	Single Pulsed Avalanche End	ergy	(Note 2)	2) 211.6		mJ	
I <sub>AR</sub>	Avalanche Current		(Note 1)	2.3		Α	
E <sub>AR</sub>	Repetitive Avalanche Energy	,	(Note 1)	1) 1.06		mJ	
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	3) 20		1//	
uv/ui	MOSFET dv/dt			1	00	V/ns	
D	Dower Discinction	$(T_C = 25^{\circ}C)$		106	31	W	
$P_{D}$	Power Dissipation	- Derate above 25°C		0.85	0.25	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temp	perature Range	Range -55 to +150		οС		
T <sub>L</sub> Drain current lim	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		00	°C			

#### **Thermal Characteristics**

Symbol	Parameter	FCP380N60	FCPF380N60	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.18	4	
$R_{\theta CS}$	Thermal Resistance, Case to Heat Sink (Typical)		0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	62.5	

# **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCP380N60	FCP380N60	TO-220	-	-	50
FCPF380N60	FCPF380N60	TO-220F	-	-	50

# **Electrical Characteristics** T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charae	cteristics					
D\/	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 25^{\circ}\text{C}$	600	-	-	V
BV <sub>DSS</sub> Drain to Source Breakdown Voltage	Dialii to Source Breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 150^{\circ}\text{C}$	650	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 10 mA, Referenced to 25°C	-	0.6	-	V/°C
BV <sub>DS</sub>	Drain-Source Avalanche Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 10 A	-	700	-	V
	Zero Gate Voltage Drain Current	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 480 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	10	μА
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA

#### On Characteristics

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.5	-	3.5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	•	0.33	0.38	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 20 \text{ V}, I_{D} = 5 \text{ A}$	ı	11		S

### **Dynamic Characteristics**

•						
C <sub>iss</sub>	Input Capacitance	V 25 V V 0 V	-	1250	1665	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}$ f = 1 MHz	-	905	1205	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1/11/12	-	45	60	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 380 \text{ V}, V_{GS} = 0 \text{ V}, f = 1.0 \text{ MHz}$	-	23	-	pF
Coss eff.	Effective Output Capacitance	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V	-	95	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	V <sub>DS</sub> = 380 V, I <sub>D</sub> = 5 A	-	30	40	nC
$Q_{gs}$	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V	-	5	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge	(Note 4)	-	10	-	nC
ESR	Equivalent Series Resistance	Drain Open		1		Ω

#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		-	14	38	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 380 \text{ V}, I_{D} = 5 \text{ A}$	-	7	24	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R = 4.7 \Omega$	-	45	100	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	-	6	22	ns

#### **Drain-Source Diode Characteristics**

I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current			-	10.2	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current			-	30.6	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{SD} = 5 \text{ A}$	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 5 A	-	240	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100 \text{ A/}\mu\text{s}$ - 2.7		-	μС	

#### Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2.  $I_{AS}$  = 2.3 A,  $V_{DD}$  = 50 V,  $R_{G}$  = 25  $\Omega$ , Starting  $T_{J}$  = 25°C
- 3.  $I_{SD} \le 5.1$  A, di/dt  $\le 200$  A/ $\mu$ s,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J = 25^{\circ}C$
- 4. Essentially Independent of Operating Temperature Typical Characteristics

# **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

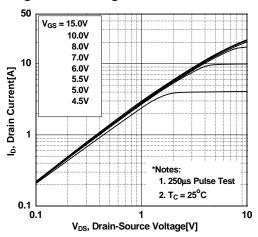


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

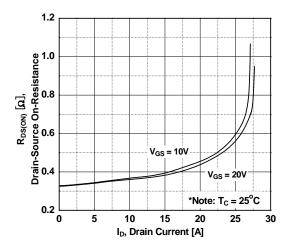


Figure 5. Capacitance Characteristics

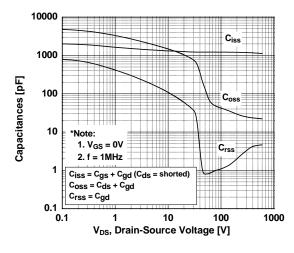


Figure 2. Transfer Characteristics

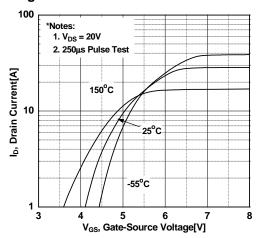


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

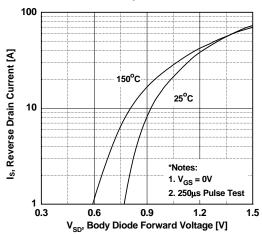
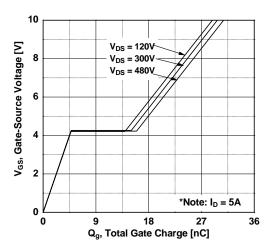


Figure 6. Gate Charge Characteristics



#### Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

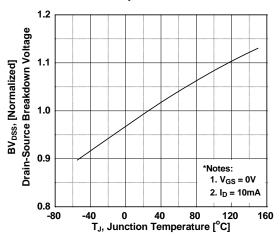
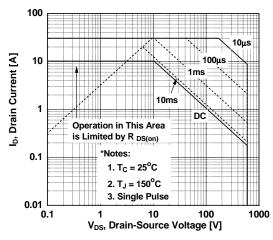


Figure 9. Maximum Safe Operating Area vs. Case Temperature - FCP380N60



**Figure 11. Maximum Drain Current** 

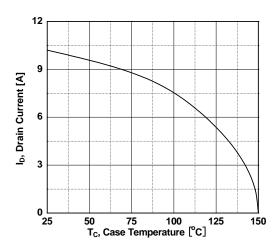


Figure 8. On-Resistance Variation vs. Temperature

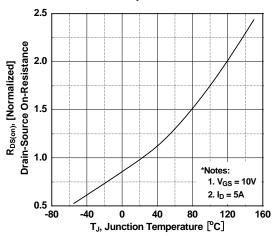


Figure 10. Maximum Safe Operating Area vs. Case Temperature - FCPF380N60

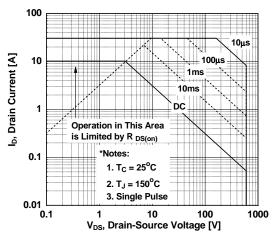
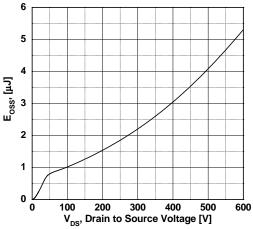


Figure 12. Eoss vs. Drain to Source Voltage Switching Capability



# **Typical Performance Characteristics** (Continued)

Figure 13. Transient Thermal Response Curve - FCP380N60

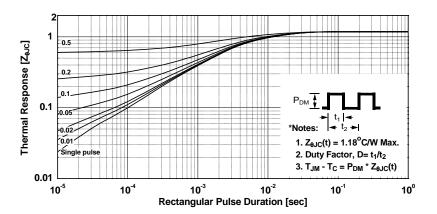
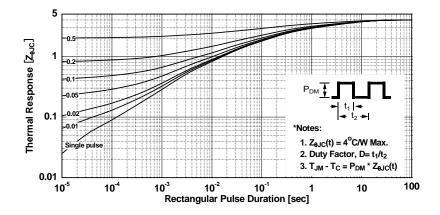
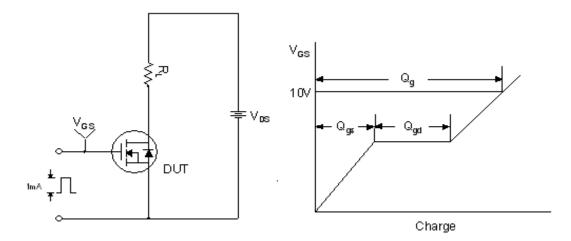


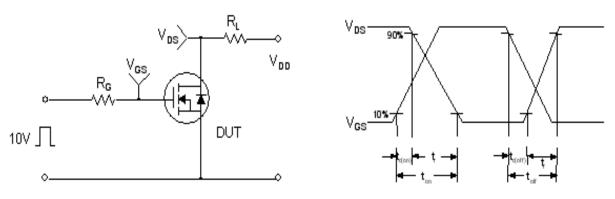
Figure 14. Transient Thermal Response Curve - FCPF380N60



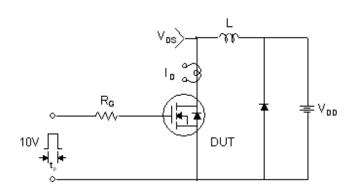
#### **Gate Charge Test Circuit & Waveform**

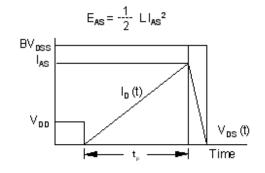


#### **Resistive Switching Test Circuit & Waveforms**

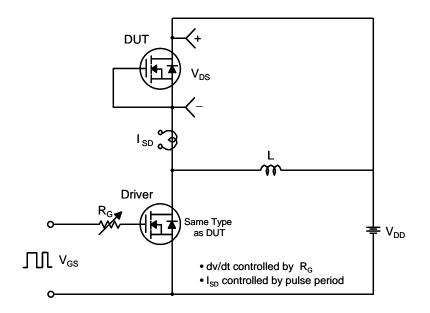


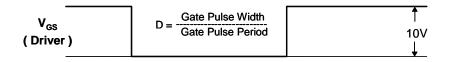
**Unclamped Inductive Switching Test Circuit & Waveforms** 

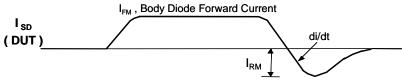




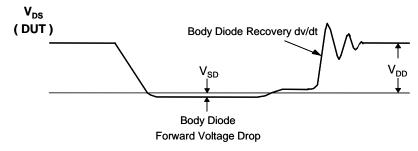
#### Peak Diode Recovery dv/dt Test Circuit & Waveforms





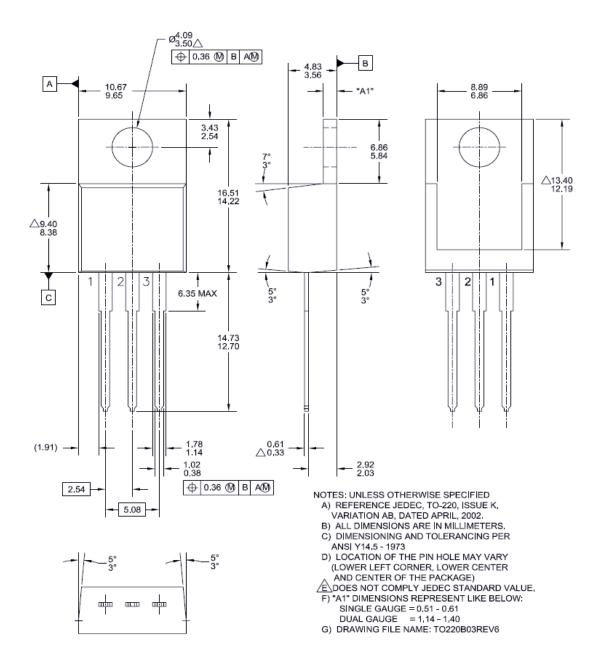


Body Diode Reverse Current



#### **Mechanical Dimensions**

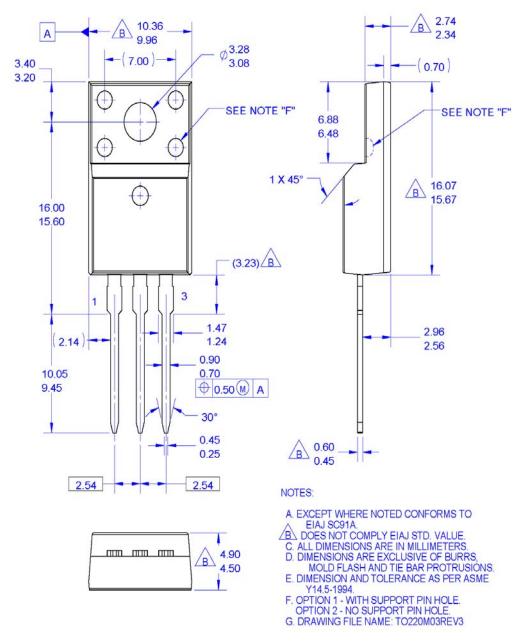
# TO-220



Dimensions in Millimeters

# **Package Dimensions**

# TO-220F (Retractable)



\* Front/Back Side Isolation Voltage : AC 2500V

**Dimensions in Millimeters** 





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Rev. 164